

L Number	Hits	Search Text	DB	Time stamp
22	12197	((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:28
23	1832	((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:25
24	18	(((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)) and (250/281-300.ccls. 250/423R,424,423F.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:10
25	122	(((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)) and (single near2 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:06
26	30	(((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)) and (single near2 chip) and ((laser near2 etching) (photolithograph\$2 (wet near2 chemical adj etching) (laser near ablation) (plasma near etching) (casting) (injection near molding) ((hot cold) near2 stamping)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:02
27	26	((((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)) and (single near2 chip) and ((laser near2 etching) (photolithograph\$2 (wet near2 chemical adj etching) (laser near ablation) (plasma near etching) (casting) (injection near molding) ((hot cold) near2 stamping))) and ((polycarbonate polyamide polymethylmethacrylate polyoxymethylene (cycloolefin adj copolymer) polyethylene polypropylene polystyrene plastic glass silicon)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:03
28	4	((((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)) and (single near2 chip) and ((laser near2 etching) (photolithograph\$2 (wet near2 chemical adj etching) (laser near ablation) (plasma near etching) (casting) (injection near molding) ((hot cold) near2 stamping))) and ((polycarbonate polyamide polymethylmethacrylate polyoxymethylene (cycloolefin adj copolymer) polyethylene polypropylene polystyrene plastic glass silicon))) and ((liquid near separation) electrophore\$3) (((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)) and (250/281-300.ccls. 250/.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:04
29	101	((((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)) and (250/281-300.ccls. 250/.ccls.)) and (single near2 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:06
30	13	(((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray))) and ((increas\$3 improv\$4) near3 current)) and (250/281-300.ccls. 250/.ccls.)) and (single near2 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:08
31	211	(array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray)) same ((increas\$3 improv\$4) near3 current)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:10
32	2	((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray)) same ((increas\$3 improv\$4) near3 current)) and (250/281-300.ccls. 250/423R,424,423F.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:24
33	115	Smith-Richard-D.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:25
34	5	Smith-Richard-D.in. and ((increas\$3 improv\$4) near3 current)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:28

35	9	Tang-Keqi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:26
36	4	Tang-Keqi.in. and ((increas\$3 improv\$4) near3 current)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:27
37	7	Lin-Yuehe.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:26
38	1	Lin-Yuehe.in. and ((increas\$3 improv\$4) near3 current)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:27
39	2	((Smith-Richard-D.in. and ((increas\$3 improv\$4) near3 current)) or (Tang-Keqi.in. and ((increas\$3 improv\$4) near3 current)) or (Lin-Yuehe.in. and ((increas\$3 improv\$4) near3 current))) and ((array multiple multi-) with ((spray adj emitters) (spray adj orifice) emitter (electrospray)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:29
-	44	(array with ((spray adj emitters) (electrospray))) and (250/281-300.ccls. 250/423R,424,423F.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 13:31
-	2	((array with ((spray adj emitters) (electrospray))) and (250/281-300.ccls. 250/423R,424,423F.ccls.)) and ((increas\$3 improv\$4) near3 current)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 13:34
-	446	staats.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 11:03
-	6	staats.in. and electrospray	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 11:03
-	124	(array with ((spray adj emitters) (electrospray)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 13:31
-	5	((array with ((spray adj emitters) (electrospray)))) and ((increas\$3 improv\$4) near3 current)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 12:03
-	1	((((array with ((spray adj emitters) (electrospray)))) and ((increas\$3 improv\$4) near3 current)) and multi-capillary	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 12:04
-	4	((((array with ((spray adj emitters) (electrospray)))) and ((increas\$3 improv\$4) near3 current)) and (single near2 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:01
-	4	(((array with ((spray adj emitters) (electrospray)))) and ((increas\$3 improv\$4) near3 current)) and (single near2 chip)) and ((laser near2 etching) (photolithograph\$2 (wet near2 chemical adj etching) (laser near ablation) (plasma near etching) (casting) (injection near molding) ((hot cold) near2 stamping)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:02

		4 (((((array with ((spray adj emitters) (electrospray))))) and ((increas\$3 improv\$4 near3 current)) and (single near2 chip)) and ((laser near2 etching) (photolithograph\$2 (wet near2 chemical adj etching) (laser near ablation) (plasma near etching) (casting) (injection near molding) ((hot cold) near2 stamping)))) and ((polycarbonate polyamide polymethylmethacrylate polyoxymethylene (cycloolefin adj copolymer) polyethylene polypropylene polystyrene plastic glass silicon)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:03
		4 (((((array with ((spray adj emitters) (electrospray))))) and ((increas\$3 improv\$4 near3 current)) and (single near2 chip)) and ((laser near2 etching) (photolithograph\$2 (wet near2 chemical adj etching) (laser near ablation) (plasma near etching) (casting) (injection near molding) ((hot cold) near2 stamping)))) and ((polycarbonate polyamide polymethylmethacrylate polyoxymethylene (cycloolefin adj copolymer) polyethylene polypropylene polystyrene plastic glass silicon))) and ((liquid near separation) electrophore\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/03 14:04